12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20250520001.1
Qualification of a new Die Attach material for select devices
Change Notification / Sample Request

Date: May 21, 2025
To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

20250520001.1
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records**,** you have recently purchased these devices**.** The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
TMS320C25GBL	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20250520001.1	**PCN Date:**	May 21, 2025
Title:	Qualification of a new Die Attach material for select devices		
Customer Contact:	Change Management team	**Dept:**	Quality Services
Proposed 1st Ship Date:	August 19, 2025	**Sample requests accepted until:**	July 20, 2025

***Sample requests received after** July 20, 2025 **will not be supported.**

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Material
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Process
☒	Assembly Materials	☐	Part number change	☐	Wafer Fab Site
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Material
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Process

PCN Details

Description of Change:

This PCN is to inform of an alternate die attach qualification for the devices in the product affected section as follows:

What	Current	New
Mount Compound	4073502	4229187

Reason for Change:

Continuity of supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
☒ No Change	☒ No Change	☒ No Change	☒ No Change

Changes to product identification resulting from this PCN:

None

Product Affected:

5962-8861901XA	5962-9466902QXC	SM320C40GFS60	SMJ320C40GFM40
5962-8861901YA	5962-9466903QXA	SM320C80GFM50	SMJ320C40GFM50
5962-8861901ZA	5962-9466903QXC	SM34020AGBM32	SMJ320C40GFS60
5962-8861902XA	5962-9466904QXA	SM34020AGBM40	SMJ320C50GFAM50
5962-8861902ZA	5962-9679101QXA	SM34020AGBS40	SMJ320C50GFAM50CS
5962-9162303MXA	MPD23772GFA	SMJ320C25-50FJM	SMJ320C50GFAM66
5962-9162303MXC	SM320C25GBM	SMJ320C25-50GBM	SMJ320C80GFM50
5962-9162304MXA	SM320C26BFJM	SMJ320C25FDM	SMJ34020AGBM32
5962-9162304MXC	SM320C30GEL	SMJ320C25FJM	SMJ34020AGBM40
5962-9205803MXA	SM320C30GEL40NG	SMJ320C25GBM	TMS320C25GBA
5962-9205804MXA	SM320C30GEL50	SMJ320C31GFAM40	TMS320C25GBL
5962-9205805QXA	SM320C31GFAM50	SMJ320C31GFAM40CS	

5962-9455803QXA	SM320C40GFM40	SMJ320C31GFAM50	
5962-9466902QXA	SM320C40GFM50	SMJ320C31GFAS60	

Qualification Report

QMLP New Product Qualification Summary

EPD LCCC 68FD: New die attach material

Approve Date 30-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Spec	Test Name	Condition	Qual Device: SMJ320C25FDM
Group B Tests (Mechanical and Environmental Test)				
B2	TM 2011	Bond Strength	22 bonds / lot, min 4 devices	1/4/0
B2	TM 2019	Die Shear	See note	1/3/0
Characterization				
Char	-	Characterization	Per Device Specification	Pass
Group D tests (Package Related Tests)				
D3	TM 1011	Thermal Shock	Thermal Shock B QML -55C/125C	1/15/0
D3	TM 1010	Temp Cycle	TC C QML D3 65C/150C	1/15/0
D3	TM 1004	Moisture Resistance QML	Per 883 TM1004	1/15/0
D3	TM 1004/1010	Visual Examination QML D3	Per 883 TM1004 or TM1010	1/15/0
D3	TM 1014	Seal (Leak) Test QML	Fine and Gross	1/15/0
D3	-	End Point Electrical Parameters	25 degrees C, per data sheet	1/15/0
D3	TM 2002	Mechanical Shock QML	Condition B per 883 TM2002	1/15/0
D4	TM 2007	Vibration QML	Condition A minimum, per 883 TM2007	1/15/0
D4	TM 2001	Constant Acceleration QML	Condition E, Y1 orientation only, per 883 TM2001	1/15/0
D4	TM 1014	Seal (Leak) Test QML	Fine and Gross	1/15/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SMJ320C25FDM is qualified at NOT CLASSIFIED NOT CLASSIFIED
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Qualified per MIL-PRF-38535 and optimizations as aligned with DLA and documented in the QM Plan.
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2401-012

QMLP New Product Qualification Summary

JLCC New die attach material
Approve Date 30-APRIL -2025

Qualification Results
Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Spec	Test Name	Condition	Qual Device: SM320C26BFJM
Group B Tests (Mechanical and Environmental Test)				
B2	TM 2011	Bond Strength	22 bonds / lot, min 4 devices	1/4/0
B2	TM 2019	Die Shear	See note	1/3/0
Characterization				
Char	-	Characterization	Per Device Specification	Pass
Group D tests (Package Related Tests)				
D3	TM 1011	Thermal Shock	Thermal Shock B QML -55C/125C	1/15/0
D3	TM 1010	Temp Cycle	TC C QML D3 65C/150C	1/15/0
D3	TM 1004	Moisture Resistance QML	Per 883 TM1004	1/15/0
D3	TM 1004/1010	Visual Examination QML D3	Per 883 TM1004 or TM1010	1/15/0
D3	TM 1014	Seal (Leak) Test QML	Fine and Gross	1/15/0
D3	-	End Point Electrical Parameters	25 degrees C, per data sheet	1/15/0
D3	TM 2002	Mechanical Shock QML	Condition B per 883 TM2002	1/15/0
D4	TM 2007	Vibration QML	Condition A minimum, per 883 TM2007	1/15/0
D4	TM 2001	Constant Acceleration QML	Condition E, Y1 orientation only, per 883 TM2001	1/15/0
D4	TM 1014	Seal (Leak) Test QML	Fine and Gross	1/15/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SM320C26BFJM is qualified at NOT CLASSIFIED NOT CLASSIFIED
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Qualified per MIL-PRF-38535 and optimizations as aligned with DLA and documented in the QM Plan.
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2403-041

QMLP New Product Qualification Summary

Die-Attach Conversion for EPD CPGA Ceramic PKG

Approve Date 30-APRIL -2025

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Spec	Test Name	Condition	Qual Device: SMJ34020AGBM32	Qual Device: SMJ320C40GFM50	Qual Device: SMJ320C25GBM
Group B Tests (Mechanical and Environmental Test)						
B2	TM 2011	Bond Strength QML	22 bonds / lot, min 4 devices	1/4/0	1/4/0	1/4/0
B2	TM 2019	Die Shear QML	-	1/3/0	1/3/0	1/3/0
Characterization						
Char	-	Characterization	Per Device Specification	Pass	Pass	Pass
Group D tests (Package Related Tests)						
D3	TM 1011	Thermal Shock	Thermal Shock B QML -55C/125C	1/15/0	1/15/0	1/15/0
D3	TM 1010	Temp Cycle	TC C QML D3 65C/150C	1/15/0	1/15/0	1/15/0
D3	TM 1004	Moisture Resistance QML	Per 883 TM1004	1/15/0	1/15/0	1/15/0
D3	TM 1004/1010	Visual Examination QML D3	Per 883 TM1004 or TM1010	1/15/0	1/15/0	1/15/0
D3	TM 1014	Seal (Leak) Test QML	Fine and Gross	1/15/0	1/15/0	1/15/0
D3	-	End Point Electrical Parameters	25 degrees C, per data sheet	1/15/0	1/15/0	1/15/0
D4	TM 2002	Mechanical Shock QML	Condition B per 883 TM2002	1/15/0	1/15/0	1/15/0
D4	TM 2007	Vibration QML	Condition A minimum, per 883 TM2007	1/15/0	1/15/0	1/15/0
D4	TM 2001	Constant Acceleration QML	Condition E, Y1 orientation only, per 883 TM2001	1/15/0	1/15/0	1/15/0
D4	TM 1014	Seal (Leak) Test QML	Fine and Gross	1/15/0	1/15/0	1/15/0
D4	TM 2007	Visual Examination QML D4	Per TM2007	1/15/0	1/15/0	1/15/0
D4	-	End Point Electrical Parameters	25 degrees C, per data sheet	1/15/0	1/15/0	1/15/0
D6	TM 1018	Internal Gas Analysis	Cavity packaged devices only. 5,000 ppm maximum water content at 100C.	1/3/0	1/3/0	1/3/0
Assembly MQ						
MQ	-	Assembly MQ	Per site specification	1/1/0	1/1/0	1/1/0

QBS: Qual By Similarity, also known as Generic Data
Qual Device SMJ34020AGBM32 is qualified at NOT CLASSIFIED NOT CLASSIFIED
Qual Device SMJ320C40GFM50 is qualified at NOT CLASSIFIED NOT CLASSIFIED
Qual Device SMJ320C25GBM is qualified at NOT CLASSIFIED NOT CLASSIFIED
Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles
Qualified per MIL-PRF-38535 and optimizations as aligned with DLA and documented in the QM Plan.
Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

TI Qualification ID: R-CHG-2304-054

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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